

# SDS21WAF

## High Voltage Switching Diode

#### **General Description**

Dual general-purpose switching diodes, fabricated in planar technology, and packaged in small SOT-23F surface mounted device (SMD) packages.

#### **Features and Benefits**

- Silicon epitaxial planar diode
- · High switching speed
- · Low forward drop voltage and low leakage current
- "Green" device and RoHS compliant device
- Available in full lead (Pb)-free device



SOT-23F





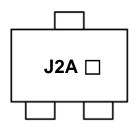
#### **Applications**

• Ultra high speed switching application

#### **Ordering Information**

Part Number	Marking Code	Package	Packaging
SDS21WAF	J2A □	SOT-23F	Tape & Reel

#### **Marking Information**



J2A = Specific Device Code

□ = Year & Week Code Marking

#### **Pinning Information**

Pin	Description	Simplified Outline	Graphic Symbol
1	Cathode (Diode 1)	3	
2	Cathode (Diode 2)		<b>*</b> *
3	Common Anode	1 2	<del>'                                    </del>

#### **Absolute Maximum Ratings** (T<sub>amb</sub>=25°C, Unless otherwise specified)

Characteristic	Symbol	Ratings	Unit
Maximum repetitive peak reverse voltage	$V_{RM}$	250	V
Continuous reverse voltage	V <sub>R</sub>	200	V
Maximum average forward rectified current	Io	200	mA
Maximum repetitive peak forward current	I <sub>FM</sub>	400	mA
Non-repetitive peak forward surge current(t=10ms)	I <sub>FSM</sub>	1.7	А
Power dissipation 1)	P <sub>D</sub>	250	mW

<sup>1)</sup> Device mounted on FR-4 board with recommended pad layout.

#### Thermal Characteristics (T<sub>amb</sub>=25°C, Unless otherwise specified)

Characteristic	Symbol	Ratings	Unit
Thermal resistance, junction to ambient 1)	$R_{\text{th(j-a)}}$	500	°C/W
Operating junction temperature	Tj	150	°C
Storage temperature range	T <sub>stg</sub>	-55 ~ 150	°C

<sup>1)</sup> Device mounted on FR-4 board with recommended pad layout.

#### **Electrical Characteristics** (T<sub>amb</sub>=25°C, Unless otherwise specified)

Characteristic	Symbol	Test Condition	Min.	Тур.	Max.	Unit
Reverse breakdown voltage	$V_{BR}$	I <sub>F</sub> =100uA	250	-	-	V
Forward drop voltage <sup>2)</sup>	$V_{F}$		1.0	V		
	V F	I <sub>F</sub> =200mA	-	-	1.25	V
Reverse leakage current 3)		V <sub>R</sub> =200V	-	-	100	nA
	l <sub>R</sub>	V <sub>R</sub> =200V, Ta=150°C		100	uA	
Total capacitance	Ст	V <sub>R</sub> =0V, f=1MHz	-	-	5	pF
Reverse recovery time	t <sub>rr</sub>	$I_F=I_R=30$ mA, $I_{rr}=3$ mA, $R_L=100$ Ω	-	-	50	ns

<sup>&</sup>lt;sup>2)</sup> Pulse test: t<sub>P</sub>≤380 µs, Duty cycle≤2%

 $<sup>^{3)}</sup>$  Pulse test:  $t_P \le 5 ms$ , Duty cycle  $\le 2\%$ 

#### **Rating and Characteristic Curves**

Fig. 1) Typical Forward Characteristics

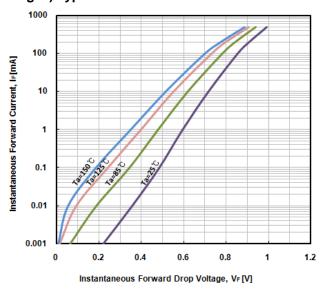


Fig. 2) Typical Reverse Characteristics

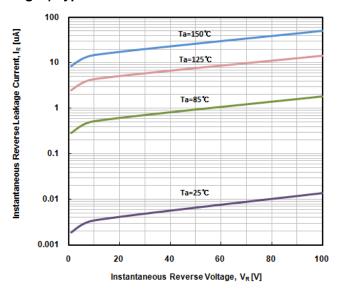


Fig. 3) Typical Total Capacitance Characteristics

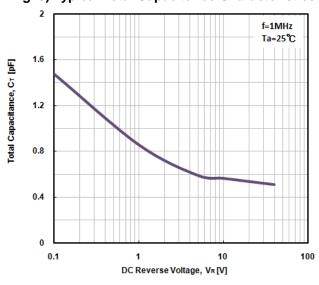


Fig. 4) Power Dissipation vs. Ambient Temperature

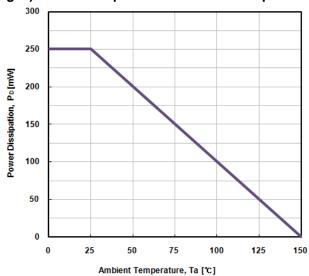
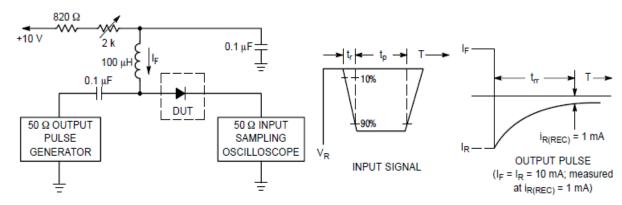
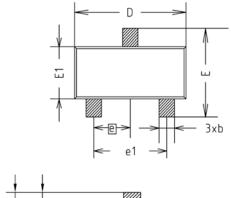
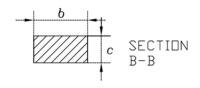


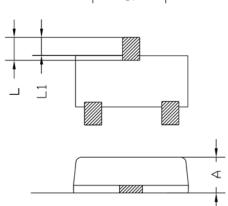
Fig. 5) Reverse recovery time equivalent test circuit

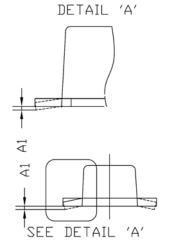


### **Package Outline Dimensions**



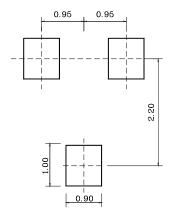






SYMBOL	YMROI MILLIMETER(mm)			NOTE
STADOL	MINIMUM	NOMINAL	MAXIMUM	NUIE
Α	0.80	0.90	1.00	
A1	0.00	-	0.10	
b	0.35	0.40	0.45	
C	0.10	0.15	0.20	
D	2.80	2.90	3.00	
E	2.30	2.40	2.50	
E1	1.50	1.60	1.70	
е	0.95BSC			
e1	1.80	1.90	2.00	
L	0.48	0.58	0.68	
L1	0.30	_	0.50	

#### **X Recommend PCB solder land (Unit: mm)**



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